

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------|------------------|
| 20 | 4 | ((rie etch\$6) with (low adj temperature)) with ((below less) near (zero degree celsius)) | USPAT; US-PGPUB | 2004/06/25 17:21 |
| 21 | 63 | (semiconductor wafer silicon substrate) and (pattern\$4 resist photoresist lithograph\$7 photolithograph\$7) and ((hole open\$4 aperture) same (taper\$3 isotropic\$6 slant\$4 angl\$4) same mask\$4 same ((organic flare silk polyimide) with (dielectric insulat\$4))) | USPAT; US-PGPUB | 2004/06/25 17:27 |
| 22 | 142 | (438/620.ccls. 438/637.ccls. 438/640.ccls. 438/669.ccls. 438/671.ccls. 438/673.ccls. 438/780.ccls.) and ((semiconductor wafer silicon substrate) and (pattern\$4 resist photoresist lithograph\$7 photolithograph\$7) and ((hole open\$4 aperture) same (taper\$3 isotropic\$6 slant\$4 angl\$4) same mask\$4 same (organic flare silk polyimide dielectric insulat\$4))) | USPAT; US-PGPUB | 2004/06/25 17:35 |
| 23 | 80 | (pattern\$4 resist photoresist lithograph\$7 photolithograph\$7) and ((hole open\$4 aperture) with (taper\$3 isotropic\$6 slant\$4 angl\$4)) and mask\$4 and (organic flare silk polyimide) | EPO; JPO; DERWENT; IBM_TDB | 2004/06/25 17:41 |
| 24 | 9 | (dual adj hard adj mask) with organic | USPAT; US-PGPUB | 2004/06/25 17:44 |
| 25 | 62 | dual adj hard adj mask | USPAT; US-PGPUB | 2004/06/25 17:46 |
| 26 | 11 | 5981913.URPN. | USPAT | 2004/06/25 17:50 |
| 27 | 3757 | 438/620.ccls. 438/637.ccls. 438/640.ccls. 438/669.ccls. 438/671.ccls. 438/673.ccls. 438/780.ccls. | USPAT; US-PGPUB | 2004/06/25 17:51 |
| 28 | 811 | (438/620.ccls. 438/637.ccls. 438/640.ccls. 438/669.ccls. 438/671.ccls. 438/673.ccls. 438/780.ccls.) and (hole open\$4 aperture) and (taper\$3 isotropic\$6 slant\$4 angl\$4) and (mask\$4 resist photoresist) | USPAT; US-PGPUB | 2004/06/25 17:52 |
| 29 | 0 | 6649517.URPN. | USPAT | 2004/06/25 17:55 |
| 30 | 14 | ("4888087" "4978420" "5109267" "5786276" "5821141" "5915198" "6025259" "6037248" "6103619" "6114243" "6303498" "6369008" "6384480" "6448183" "2002/0031901").PN. | USPAT | 2004/06/25 17:55 |